

WIRING SUBSTRATE, METHOD OF MANUFACTURING THE SAME
AND SEMICONDUCTOR DEVICE

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ABSTRACT OF THE DISCLOSURE

10 A wiring substrate equipped with a rerouted wiring
having one end connected to an electronic-part mounting
pad for electrically connecting an electronic part and
another end connected to an external-connection terminal.
In the wiring substrate, a low-elasticity underlayer made
15 of a material having a lower modulus of elasticity than
that of a base material of the wiring substrate is
disposed between the base material of the wiring
substrate and each of the electronic-part mounting pad
and the rerouted wiring. A method of manufacturing the
wiring substrate and a semiconductor device using the
20 wiring substrate are also disclosed.

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